

Product Summary

Part Number	R1 (NOM)	Marking
DDTC113TLP	1kΩ	N4

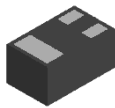
Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

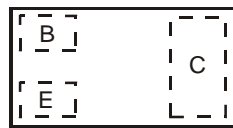
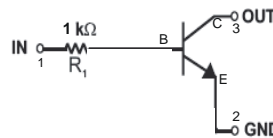
Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu
- Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.0009 grams (Approximate)

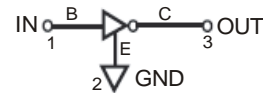
X1-DFN1006-3



Bottom View


 Top View
Pin-Out


Device Symbol


 Equivalent Inverter
Circuit

Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTC113TLP-7	N4	7	8	3,000
DDTC113TLP-7B	N4	7	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information

DDTC113TLP-7	<p>Top View Dot Denotes Collector Side</p> <p>Top View Bar Denotes Base and Emitter Side</p>
DDTC113TLP-7B	<p>Top View Bar Denotes Base and Emitter Side</p> <p>N4 = Product Type Marking Code</p>

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	50	V
Input Voltage	V _{IN}	-5 to +10	V
Output Current (I _o)	I _{C(MAX)}	100	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	250	mW
Power Derating above +25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5) (Equivalent to one heated junction of NPN)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Collector-Base Breakdown Voltage	BV _{CBO}	50	—	—	V	I _C = 50μA, I _E = 0
Collector-Emitter Breakdown Voltage	BV _{CEO}	50	—	—	V	I _C = 1mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	5	—	—	V	I _E = 50μA, I _C = 0
Collector-Base Cutoff Current	I _{CBO}	—	—	0.1	μA	V _{CB} = 50V, I _E = 0
Emitter-Base Cutoff Current	I _{EBO}	—	—	0.1	μA	V _{EB} = 4V, I _C = 0
ON CHARACTERISTICS (Note 6)						
DC Current Gain	h _{FE}	100	380	600	—	V _{CE} = 5V, I _C = 1mA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	—	0.25	V	I _C = 50mA, I _B = 2.5mA
Input Resistance	R ₁	0.7	1	1.3	kΩ	—
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f _T	—	250	—	MHz	V _{CE} = 10V, I _E = 5mA, f = 100MHz

- Notes:
- For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
 - Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

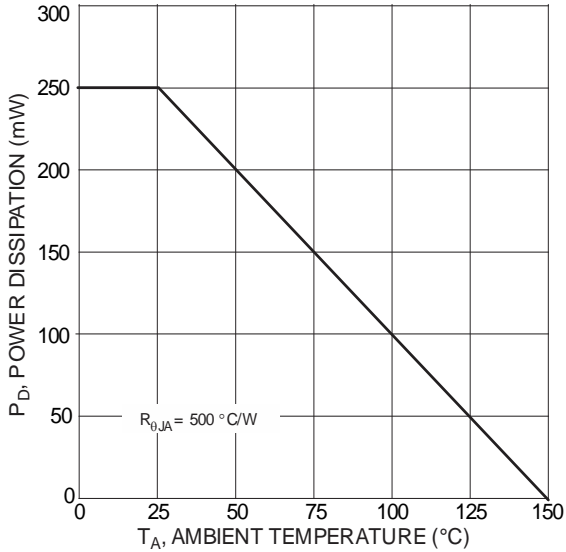


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 5)

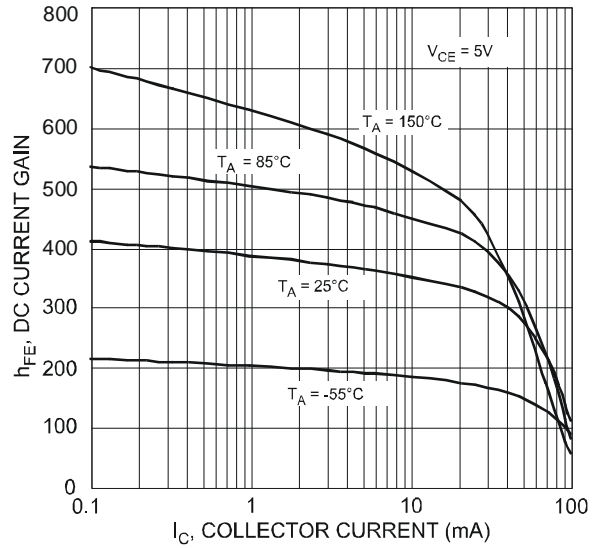


Fig. 2 Typical DC Current Gain vs. Collector Current

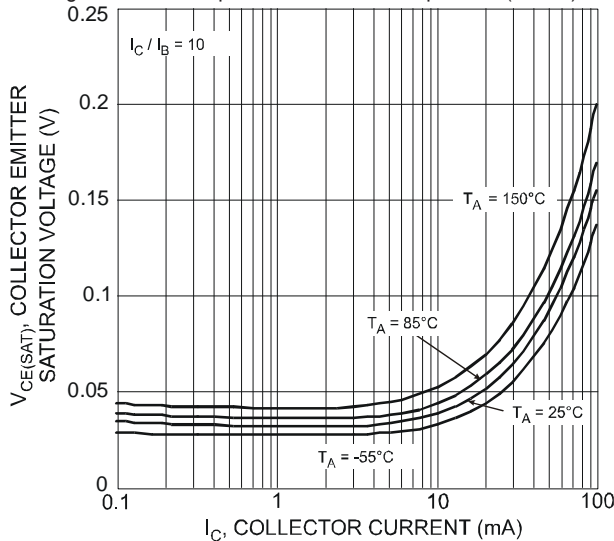


Fig. 3 Typical Collector Emitter Saturation Voltage vs. Collector Current

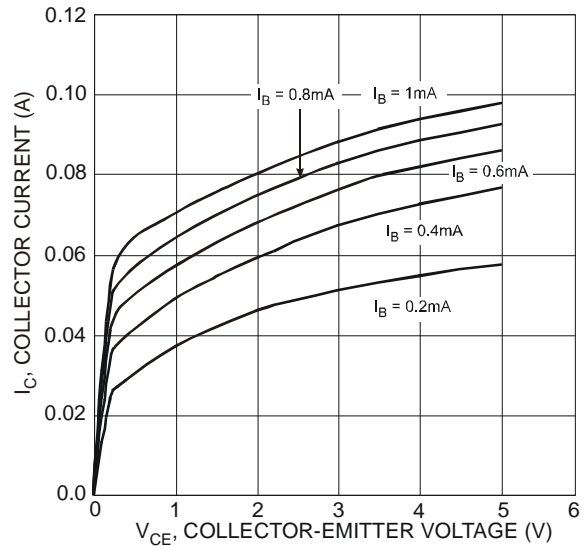


Fig. 4 Typical Collector Current vs. Collector-Emitter Voltage

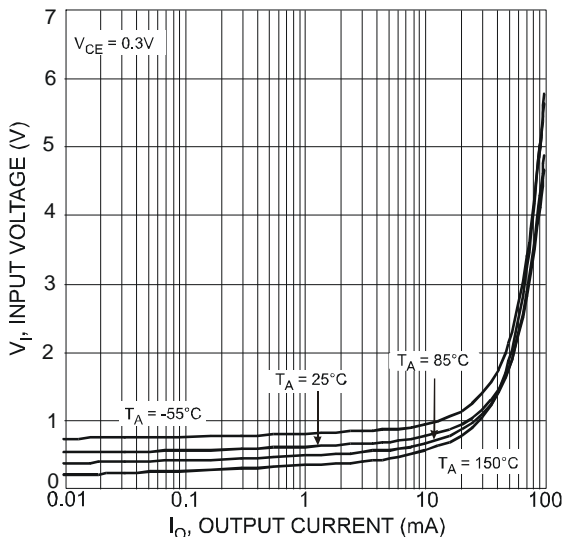


Fig. 5 Typical Input Voltage vs. Output Current (On Characteristics)

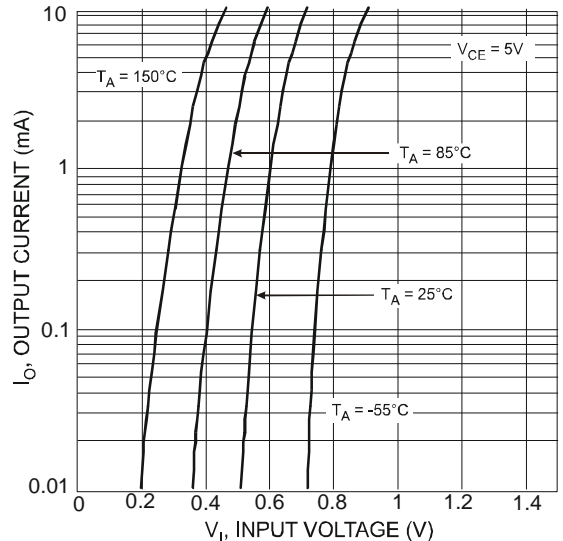
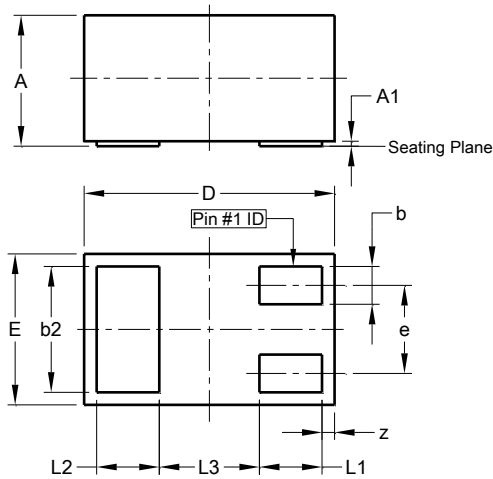


Fig. 6 Typical Output Current vs. Input Voltage (Off Characteristics)

Package Outline Dimensions

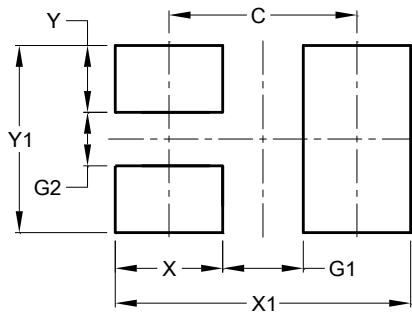
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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